

NOTES:

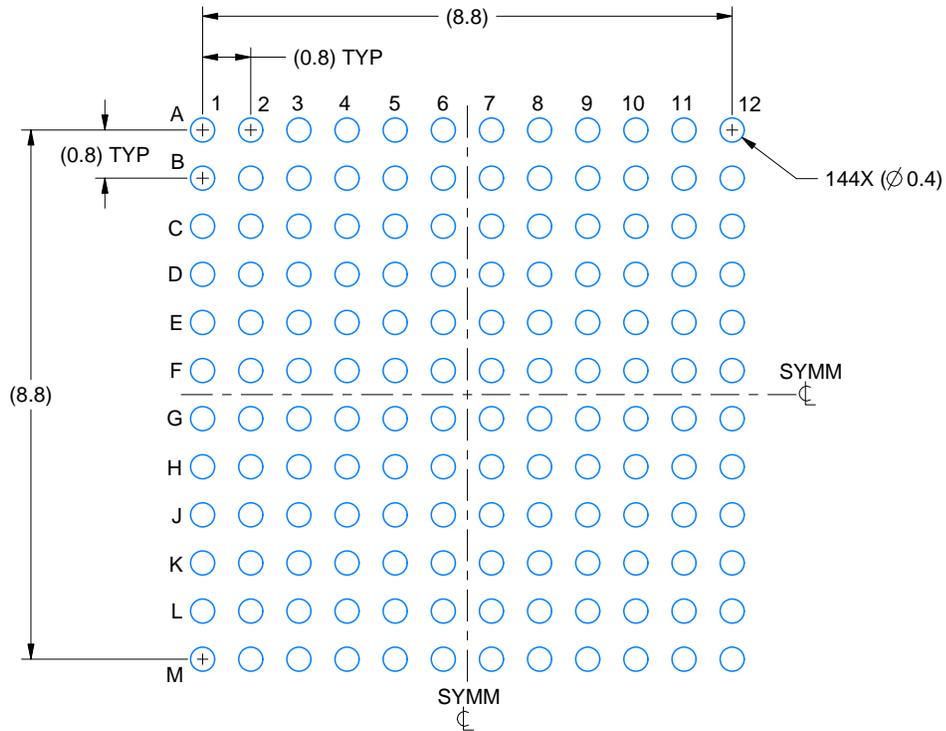
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
- Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
- The lids are electrically floating (e.g. not tied to GND).

# EXAMPLE BOARD LAYOUT

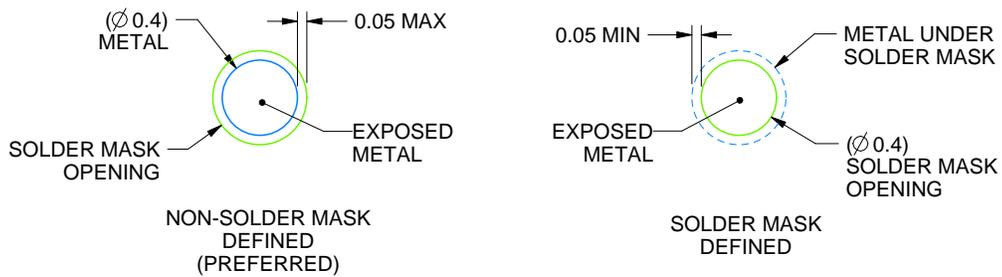
ALR0144A

FCBGA - 1.91 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 8X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

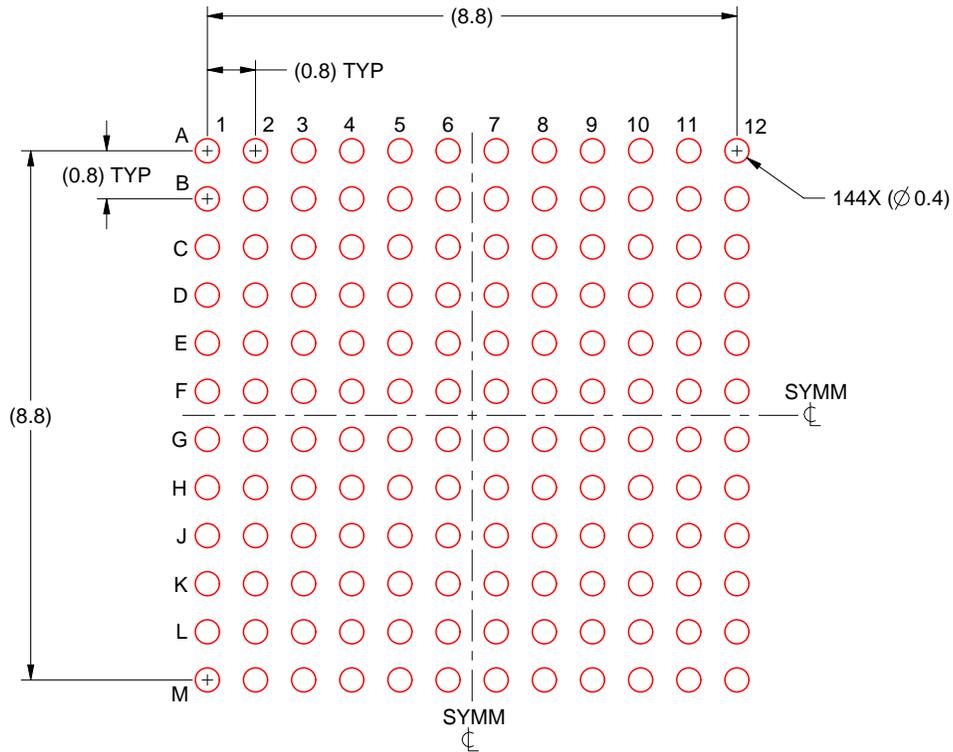
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 ([www.ti.com/lit/spru811](http://www.ti.com/lit/spru811)).

# EXAMPLE STENCIL DESIGN

ALR0144A

FCBGA - 1.91 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.15 mm THICK STENCIL  
SCALE:8X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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